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United States Patent [19]

Owens et al.

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[54] **SEMICONDUCTOR PACKAGE**

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[73] Assignee: **Motorola, Inc.**, Schaumburg, Ill.

[**] Term: **14 Years**

[21] Appl. No.: **2,224**

[22] Filed: **Dec. 3, 1992**

[52] U.S. Cl. **D13/182**

[58] **Field of Search** .... 174/52 FP; 357/70, 72, 357/74; 365/52; D13/182

[56] **References Cited**

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Mini-Circuits' YSW-2-50DR semiconductor package on p. 5 of EDN Jan. 1991.

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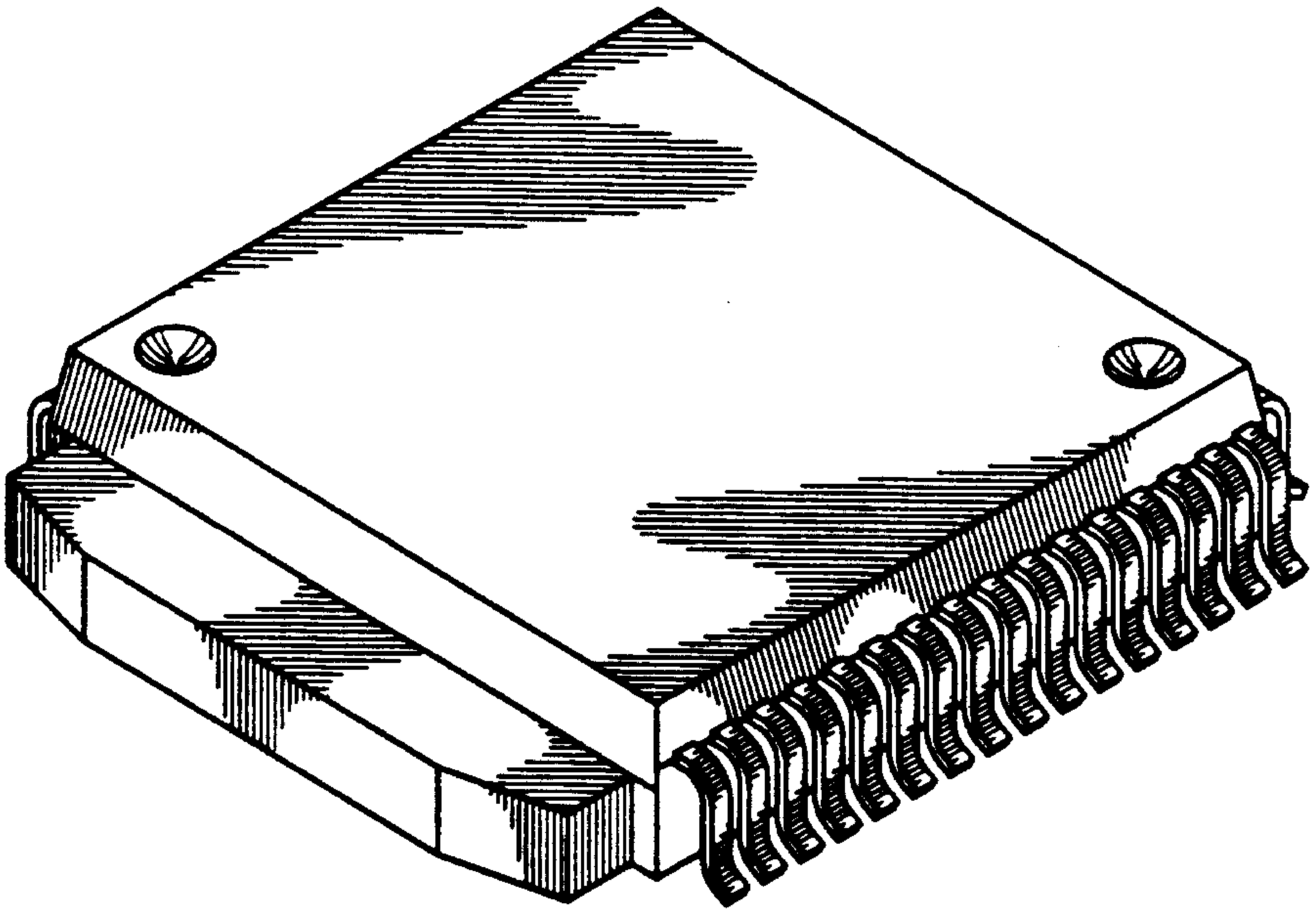
[57] **CLAIM**

The ornamental design for a semiconductor package, as shown and described.

DESCRIPTION

FIG. **1** is a front and upper right perspective view of a semiconductor package showing our new design;
FIG. **2** is a rear elevational view thereof;
FIG. **3** is a side elevational view thereof; and,
FIG. **4** is a bottom plan view thereof.



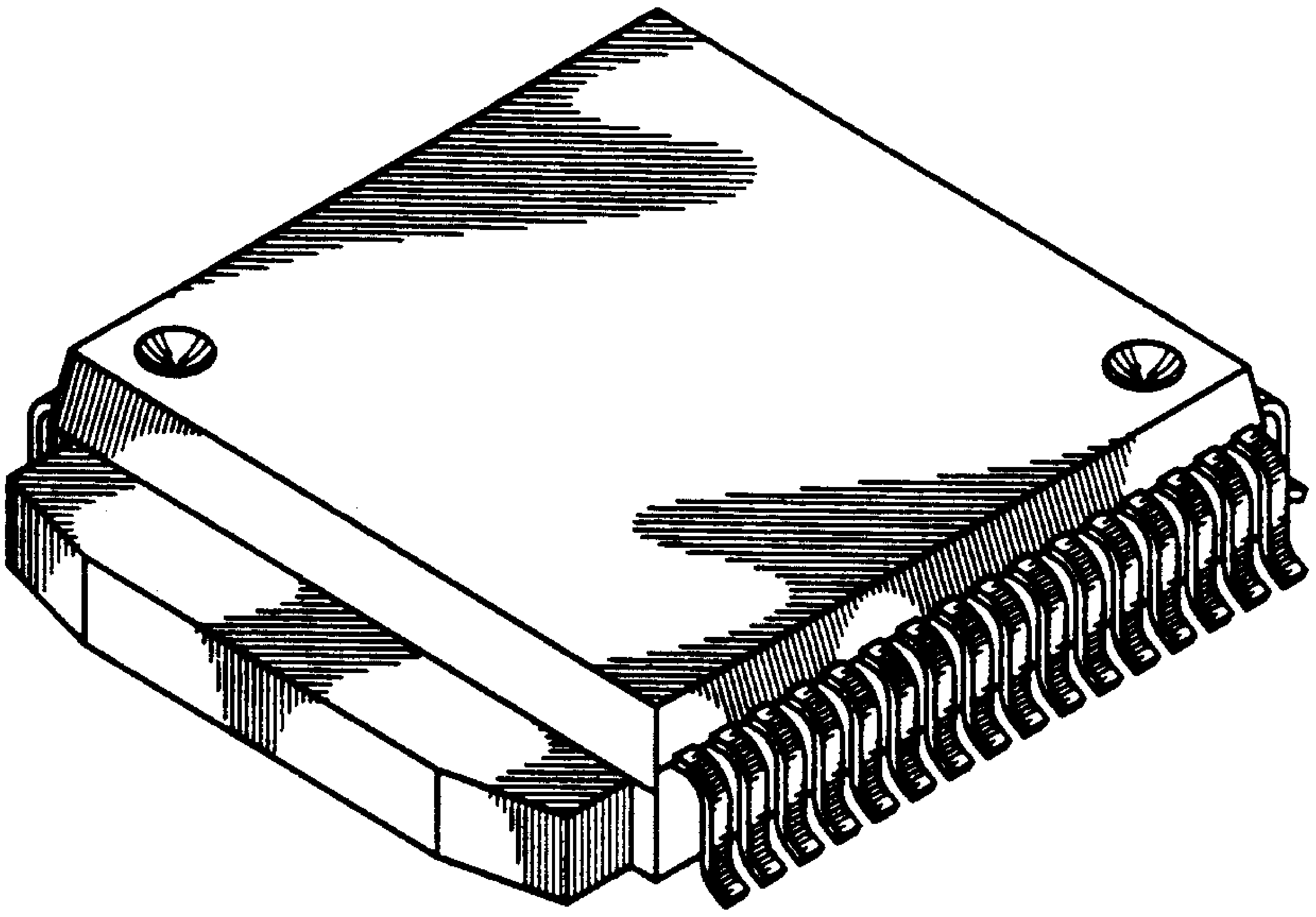


FIG. 1

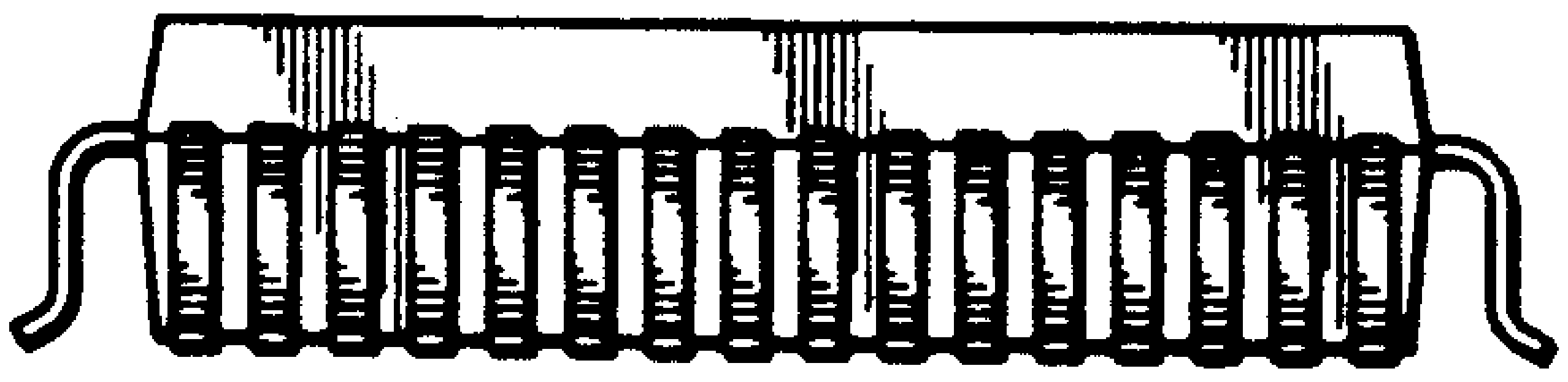


FIG. 2

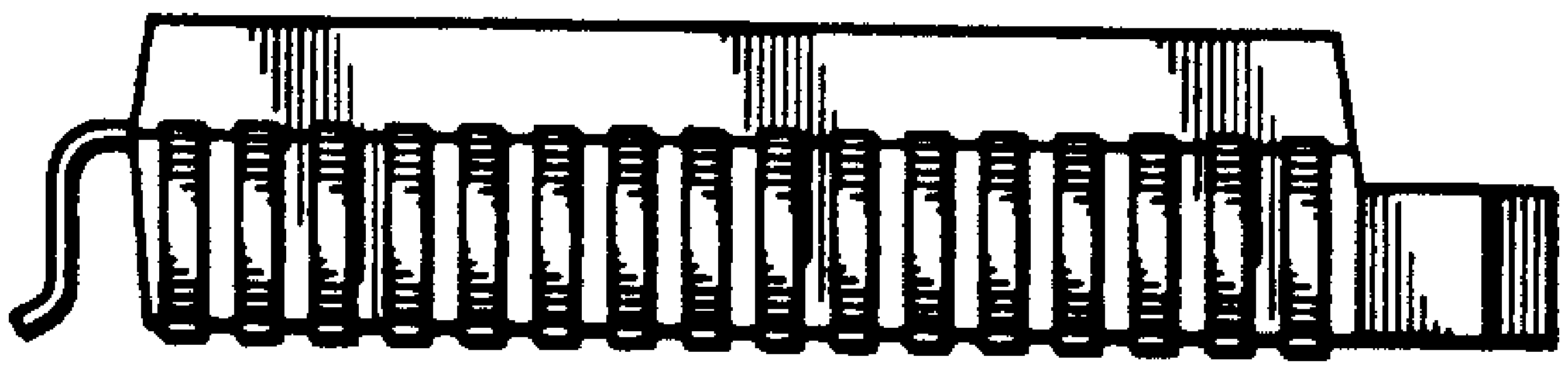


FIG. 3

FIG. 4